

1A Avg.

40 Volts

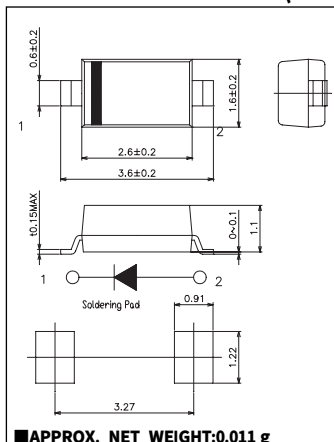
SBD

EP10QY04

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	40	V
直流順電流 Direct Forward Current	I_{DC}	$T_l = 117^\circ\text{C}$ T_l : Lead Temperature $T_a = 41^\circ\text{C}^*$	1.0 A
平均整流電流 Average Rectified Forward Current	I_o	$T_l = 123^\circ\text{C}$ VRM=0V T_l : Lead Temperature $T_a = 46^\circ\text{C}^*$ VRM=0V	0.71 A
サージ順電流 Surge Forward Current	I_{FSM}	12 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^\circ\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^\circ\text{C}$

OUTLINE DRAWING(mm)



電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j = 25^\circ\text{C}$, $V_{RM} = V_{RRM}$	—	—	1.0	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j = 25^\circ\text{C}$, $I_{FM} = 1\text{A}$	—	—	0.57	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間* Junction to Ambient*	—	—	270	$^\circ\text{C/W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	70	$^\circ\text{C/W}$

*プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 1×1 mm, Both Sides)
(T_l : Lead Temperature)

定格・特性曲線

FIG.1

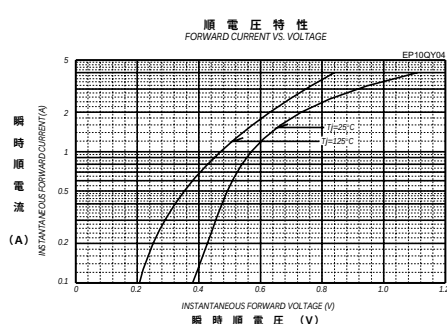


FIG.2

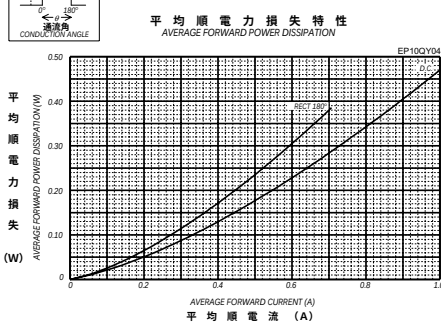


FIG.3

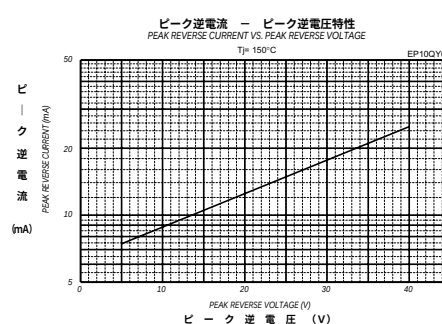


FIG.4

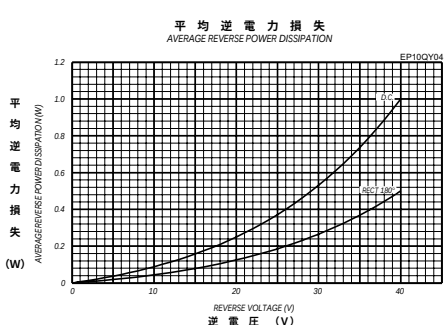


FIG.5

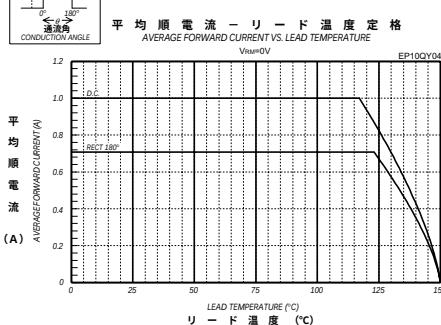


FIG.6

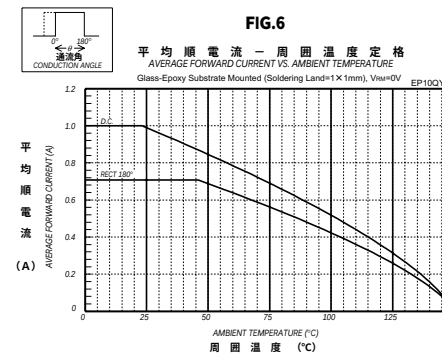


FIG.7

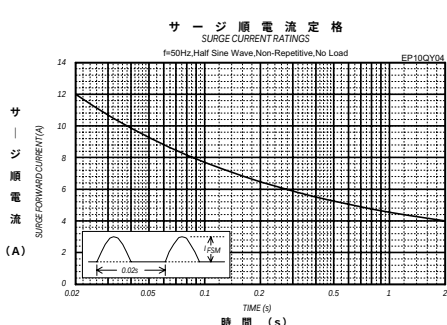


FIG.8

